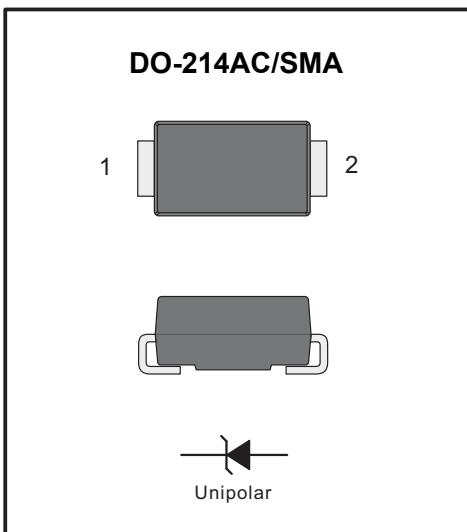


PINNING

PIN	DESCRIPTION
1	Cathode
2	Anode


Features

- ◆ For surface mounted applications
- ◆ Low profile package
- ◆ Glass Passivated Chip Junction
- ◆ Easy to pick and place
- ◆ Lead free in comply with EU RoHS 2011/65/EU directives

Mechanical Data

- ◆ Case: SMA
- ◆ Terminals: Solderable per MIL-STD-750, Method 2026
- ◆ Approx. Weight: 0.055g / 0.002oz

Maximum Ratings And Electrical Characteristics

Ratings at 25 °C ambient temperature unless otherwise specified.

Single phase half-wave 60 Hz, resistive or inductive load, for capacitive load current derate by 20 %.

Parameter	Symbols	S3A	S3B	S3D	S3G	S3J	S3K	S3M	Units
Maximum Repetitive Peak Reverse Voltage	V _{RRM}	50	100	200	400	600	800	1000	V
Maximum RMS voltage	V _{RMS}	35	70	140	280	420	560	700	V
Maximum DC Blocking Voltage	V _{DC}	50	100	200	400	600	800	1000	V
Maximum Average Forward Rectified Current at T _c = 115 °C	I _{F(AV)}				3				A
Peak Forward Surge Current 8.3 ms Single Half Sine Wave Superimposed on Rated Load	I _{FSM}				80				A
Maximum Instantaneous Forward Voltage at 3 A	V _F				1.1				V
Maximum DC Reverse Current T _a = 25 °C at Rated DC Blocking Voltage T _a = 125 °C	I _R				5 125				µA
Typical Junction Capacitance ⁽¹⁾	C _j				32				pF
Typical Thermal Resistance ⁽²⁾	R _{θJA} R _{θJC}				50 16				°C/W
Operating and Storage Temperature Range	T _j , T _{stg}				-55 ~ +150				°C

(1) Measured at 1 MHz and applied reverse voltage of 4 V D.C

(2) P.C.B. mounted with 2.0" X 2.0" (5 X 5 cm) copper pad areas.

Typical Characteristics

Fig.1 Forward Current Derating Curve

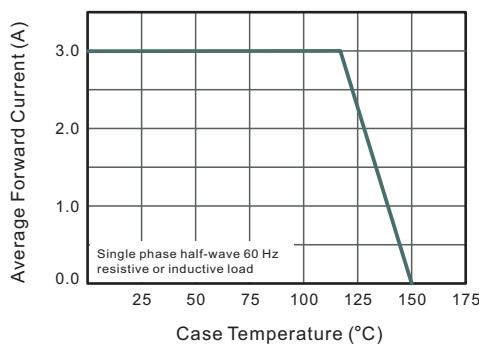


Fig.2 Typical Instantaneous Reverse Characteristics

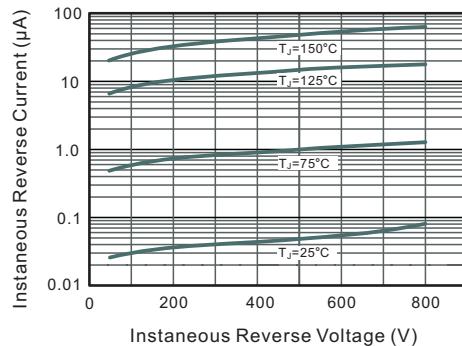


Fig.3 Typical Forward Characteristic

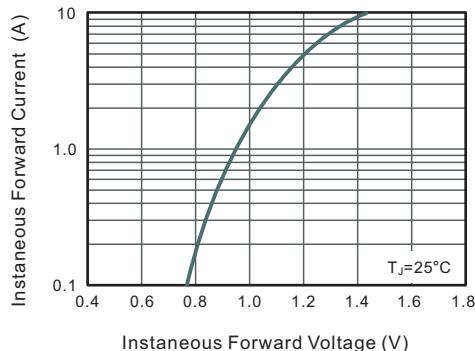


Fig.4 Typical Junction Capacitance

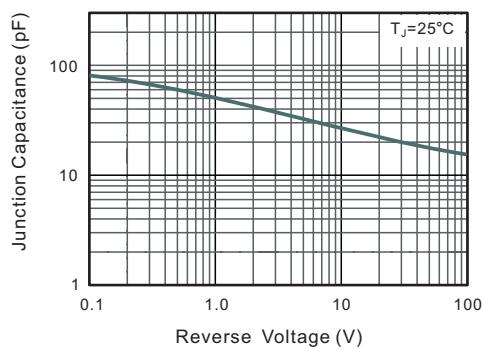
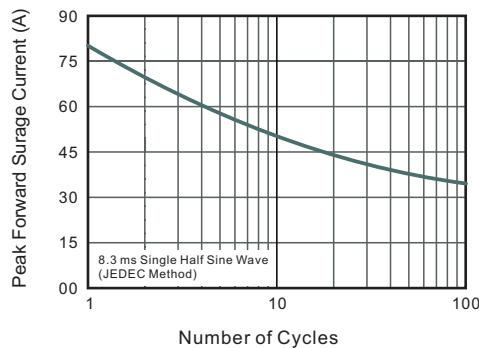


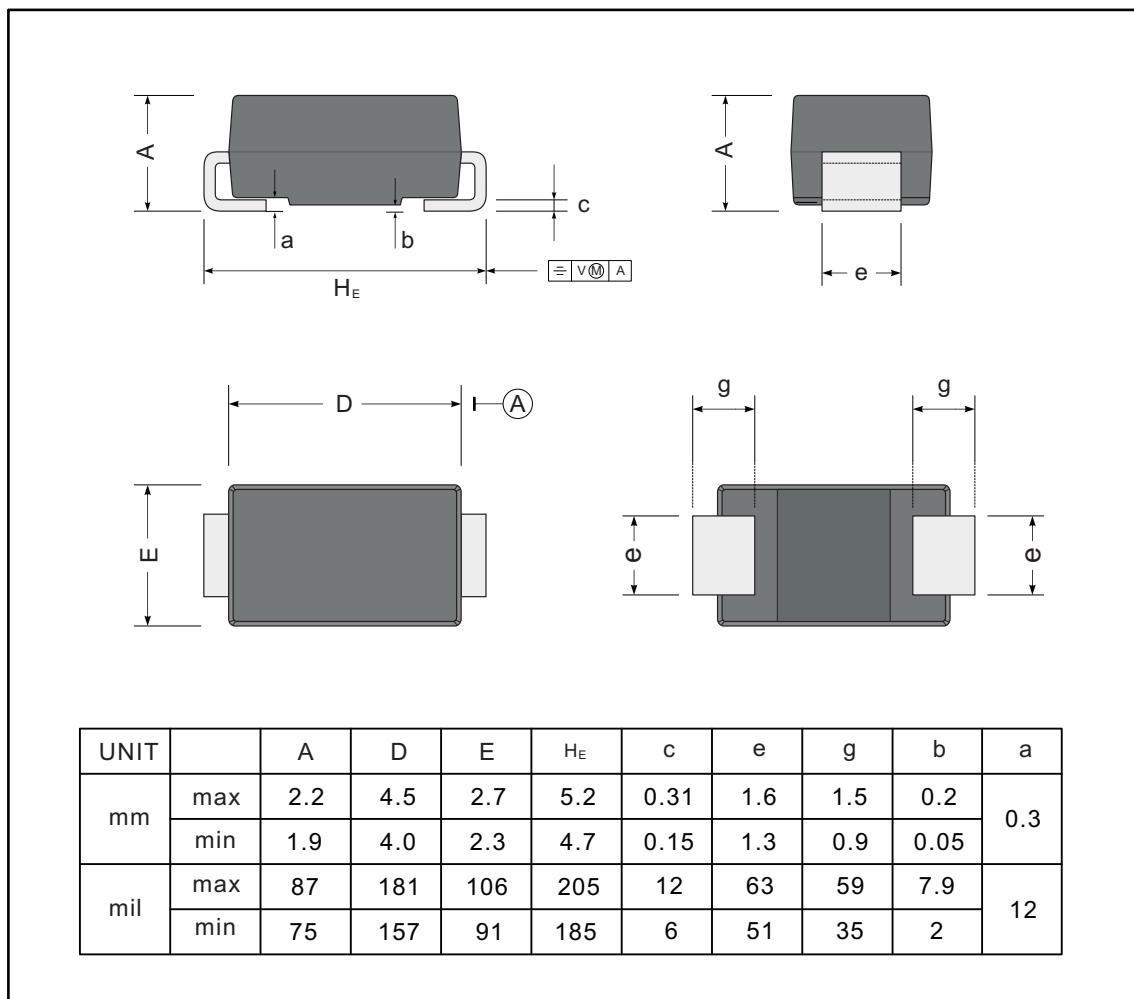
Fig.6 Maximum Non-Repetitive Peak Forward Surge Current



PACKAGE OUTLINE

Plastic surface mounted package; 2 leads

SMA



The recommended mounting pad size

